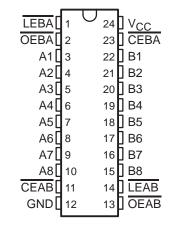
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

### description

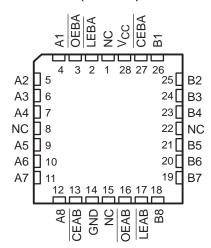
The 'ABT543 octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (\overline{LEAB}\) or \overline{LEBA}\) and output-enable (\overline{OEAB}\) or \overline{OEBA}\) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable  $(\overline{CEAB})$  input must be low in order to enter data from A or to output data from B. If  $\overline{CEAB}$  is low and  $\overline{LEAB}$  is low, the A-to-B latches are transparent; a subsequent low-to-high transition of  $\overline{LEAB}$  puts the A latches in the storage mode. With  $\overline{CEAB}$  and  $\overline{OEAB}$  both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$  inputs.

SN54ABT543 . . . JT PACKAGE SN74ABT543 . . . DB, DW, OR NT PACKAGE (TOP VIEW)



SN54ABT543 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT543 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT543 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT543 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

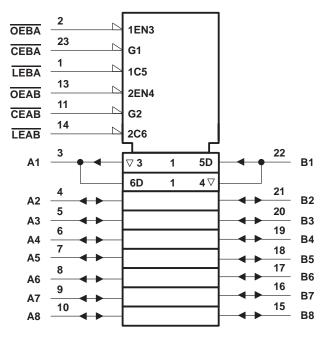
EPIC-IIB is a trademark of Texas Instruments Incorporated

#### **FUNCTION TABLE**†

	INPL	OUTPUT		
CEAB	LEAB	OEAB	Α	В
Н	Х	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в <sub>0</sub> ‡
L	L	L	L	L
L	L	L	Н	Н

<sup>†</sup> A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

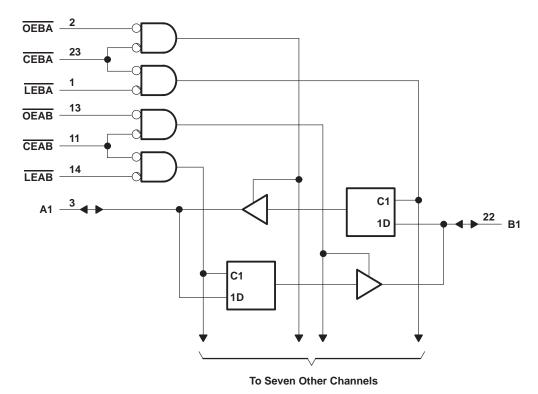
## logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, and NT packages.

<sup>‡</sup>Output level before the indicated steady-state input conditions were established.

## logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, and NT packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V <sub>O</sub>	0.5 V to 5.5 V
Current into any output in the low state, I <sub>O</sub> : SN54ABT543	96 mA
SN74ABT543	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	−50 mA
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2): DB package	0.65 W
DW package	1.7 W
NT package	1.3 W
Storage temperature range	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



## SN54ABT543, SN74ABT543 OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS157A - JANUARY 1991 - REVISED JULY 1994

## recommended operating conditions (see Note 3)

			SN54A	BT543	SN74A	LINIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	/IH High-level input voltage				2		V
V <sub>IL</sub>	Low-level input voltage					0.8	V
VI	Input voltage				0	VCC	V
lOH	OH High-level output current					-32	mA
lOL	Low-level output current	200	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	7.	5		5	ns/V
T <sub>A</sub>	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

BARAMETER	TEST CONDITIONS			Т	T <sub>A</sub> = 25°C			SN54ABT543		SN74ABT543		
PARAMETER				MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = –18 mA				-1.2		-1.2		-1.2	V	
	V <sub>CC</sub> = 4.5 V,	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		V	
V	V <sub>C</sub> C = 5 V,	$I_{OH} = -3 \text{ mA}$		3			3		3			
VOH	V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ m/s}$	1	2			2				V	
	VCC = 4.5 V	I <sub>OH</sub> = -32 mA		2*					2			
V	V 45V	I <sub>OL</sub> = 48 mA				0.55		0.55			V	
VOL	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA				0.55*		7		0.55	V	
1.	V <sub>CC</sub> = 5.5 V,		Control inputs			±1		£1		±1		
l <sub>l</sub>	$V_I = V_{CC}$ or GND		A or B ports			±100		±100		±100	μΑ	
lozh‡	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V				10§	6	10§		10§	μΑ	
lozL <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.5 V				-10§	3	-10§		-10§	μΑ	
l <sub>off</sub>	$V_{CC} = 0$ ,	V <sub>I</sub> or V <sub>O</sub> ≤ 4.5	5 V			±100	00			±100	μΑ	
ICEX	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 5.5 V	Outputs high			50	Q.	50		50	μΑ	
IO¶	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA	
	$V_{CC} = 5.5 \text{ V},$ $I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$		Outputs high		1	250		250		250	μΑ	
ICC		A or B ports	Outputs low		24	34§		34§		34§	mA	
			Outputs disabled		0.5	250		250		250	μΑ	
ΔICC <sup>#</sup>	$V_{CC} = 5.5 \text{ V}$ , One input at 3.4 V, Other inputs at $V_{CC}$ or GND				1.5		1.5		1.5	mA		
Ci	V <sub>I</sub> = 2.5 V or 0.5 V		Control inputs		4						pF	
C <sub>io</sub>	V <sub>O</sub> = 2.5 V or 0.5 V A or B ports				7						pF	

<sup>\*</sup> On products compliant to MIL-STD-883, Class B, this parameter does not apply.



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

<sup>§</sup> This data sheet limit may vary among suppliers.

<sup>¶</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT543		SN74ABT543		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub> Pulse duration, LEAB or LEBA low				3.5		3.5	Z.	3.5		ns
		Data before LEAB or LEBA↑  Data before CEAB or CEBA↑	High	3.5		3.5	Ŋ	3.5		ns
<b> </b> .	Catum time		Low	3		3	D. D. D.	3		
tsu	Setup time		High	3.5		3.5		3.5		
		Lo		3		3		3		
th	Hold time	Data after LEAB or LEBA↑  Data after CEAB or CEBA↑		1†		Ø1†		1†		
	Holu time			1†		Q 1 <sup>†</sup>		1†		ns

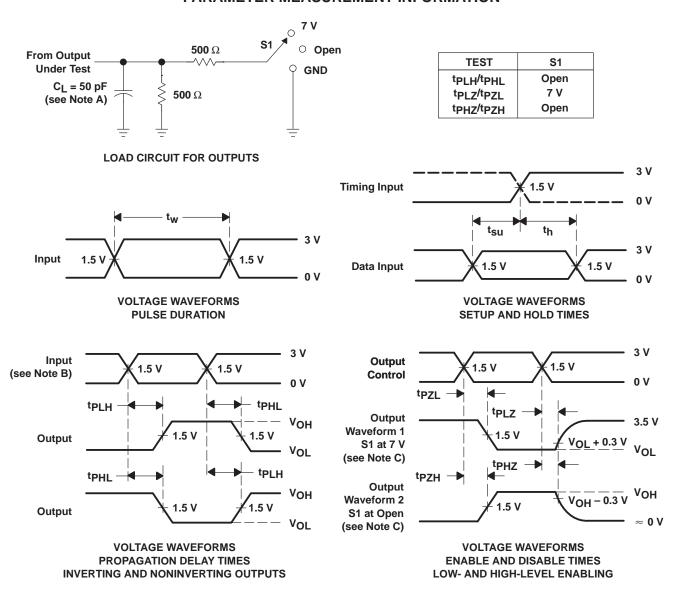
<sup>†</sup> This data sheet limit may vary among suppliers.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT543		SN74ABT543		UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	B or A	1.9	4.4	5.9	1.9		1.9	6.9	ns
<sup>t</sup> PHL	AOIB	B or A	1.9	4.4	5.9	1.9		1.9	6.9	
<sup>t</sup> PLH	LEBA or LEAB	A or B	1.6	4.1	5.6	1.6	3	1.6	6.6	ns
<sup>t</sup> PHL		AUIB	2.1	4.6	6.1	2.1	Z	2.1	7.1	110
<sup>t</sup> PZH	050	A or B	1.4	3.9	5.4	1.4	76	1.4	6.4	ns
t <sub>PZL</sub>	OEBA or OEAB	AUIB	2.5	5	6.5	2.5		2.5	7.5	115
<sup>t</sup> PHZ	OEBA or OEAB	A or B	2.5†	5.9	7.4	2.5		2.5†	8.4	ns
t <sub>PLZ</sub>	OEBA OF OEAB	AUIB	3	5.5	7	3		3	8	115
<sup>t</sup> PZH	CEBA or CEAB	A or B	1.4	3.9	5.4	2 1.4		1.4	6.4	
t <sub>PZL</sub>			2.5	5	6.5	2.5		2.5	7.5	ns
<sup>t</sup> PHZ	CEBA or CEAB	A D	3.2†	5.9	7.4	3.2†		3.2†	8.4	no
tPLZ		A or B	3	5.5	7	3		3	8	ns

<sup>†</sup>This data sheet limit may vary among suppliers.

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2.5$  ns.  $t_f \leq 2.5$  ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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